

S3088 UFI



Reliable underfill inspection

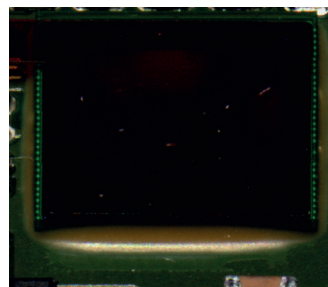
The inspection system S3088 UFI was developed specifically for reliable, cost-effective defect detection and fast process optimization. A versatile inspection concept with scalable, modular camera technology enables dependable inspection of underfillings of BGAs, Flip Chips and other components – from prototypes up to large series. By feeding electronic assemblies in and out at the same time, the Viscom FastFlow Handling ensures extremely short handling times down to a minimum of 2.5 seconds. Orthogonal cameras with a high resolution of up to 11.75 $\mu\text{m}/\text{pixel}$ guarantee consistently accurate detection even of critical defects, supported by optional side cameras with an 8 $\mu\text{m}/\text{pixel}$ resolution.

Another intelligent feature of Viscom AOI is the integrated defect verification. This feature ensures full defect detection even as it improves first pass yield. This gives system operators a convenient tool to back up a zero-escape strategy. Powerful add-on modules like off-line programming and SPC evaluation further enhance this offer.

Quick and easy inspection program generation

Viscom FastFlow Handling for extremely high throughput

High performance underfill inspection



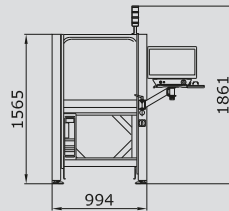
Different underfill features (bright)

AOI

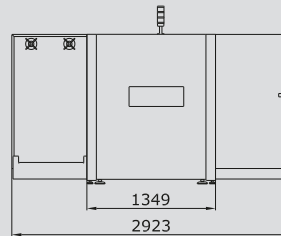
Technical Specifications



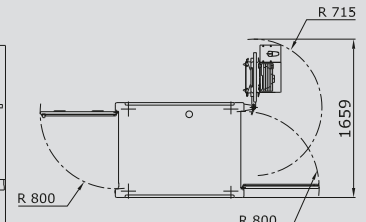
Front view



Side view



Top view



Dimensions in mm

		S3088 UFI
Inspection scope		Underfill inspection (optional: selective soldering, full-surface wave soldering, assembly inspection)
	Camera technology	8M orthogonal camera module Image field size: 57.6 mm x 43.5 mm (2.3" x 1.7") Resolution: 11.75 µm Number of megapixel cameras: 4 8M angular view module (optional) Resolution: 8 µm Number of megapixel cameras: 4 or 8
Software	User interface	Viscom EasyPro/vVision
	SPC	Viscom SPC (statistical process control), open interface (optional)
	Verification station	Viscom HARAN/vVerify
	Remote Diagnosis	Viscom SRC (optional)
	Programming station	Viscom PST34 (optional)
System computer	Operating system	Windows®
	Processor	Intel® Core™ i7
PCB handling	PCB dimensions	508 mm x 508 mm (20" x 20") (L x W)
	Transport height	900 - 950 mm ± 20 mm (35.4" - 37.4" ± 0.8")
	Width adjustment	Automatic during setup
	Transport concept	Single track transport
	PCB clamping	Pneumatic
	Upper transport clearance	50 mm (2")
	Lower transport clearance	60 mm (2.4")
Inspection speed		20 - 40 cm ² /s
Other system data	Positioning/handling unit	Synchronous linear motors
	Interfaces	SMEMA
	Power requirements	230 V (other voltages on request), 1P/N/PE, 10 A
	System dimensions	994 mm x 1565 mm x 1349 mm (39.1" x 61.6" x 53.1") (W x H x D)
	Weight	600 kg (1323 lbs)

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